Kulicke & Soffa to Present at Upcoming Taipei Investor Conference

SINGAPORE--(BUSINESS WIRE)-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) ("Kulicke & Soffa", "K&S" or the "Company"), a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment, today announced that the Company will be attending the Bank of America Merrill Lynch, Taiwan, Technology & Beyond investor conference on March 14 in Taipei, Taiwan.

Jonathan Chou, Kulicke & Soffa's interim CEO and CFO, will be accompanied by Deepak Sood, Vice President of Global Engineering and Tong Liang Cheam, Vice President of Advanced Packaging and Corporate Strategy, in representing the Company.

Additional information regarding past and future investor events is available at investor.kns.com.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a global leader in the design and manufacture of semiconductor, LED and electronic assembly equipment. As a pioneer in this industry, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, advanced SMT, wedge bonding and a broader range of expendable tools to its core ball bonding products. Combined with its extensive expertise in process technology, K&S is well positioned to help customers meet the challenges of assembling the next-generation semiconductor and LED devices. (www.kns.com)

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